

Data sheet acquired from Harris Semiconductor SCHS085E – Revised September 2003

CMOS Programmable Timer High Voltage Types (20V Rating)

Features

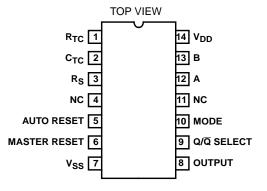
- Low Symmetrical Output Resistance, Typically 100 Ω at V_{DD} = 15V
- Built-In Low-Power RC Oscillator
- Oscillator Frequency Range..... DC to 100kHz
- External Clock (Applied to Pin 3) can be Used Instead of Oscillator
- Operates as 2^N Frequency Divider or as a Single-Transition Timer
- Q/Q Select Provides Output Logic Level Flexibility
- AUTO or MASTER RESET Disables Oscillator During Reset to Reduce Power Dissipation
- Operates With Very Slow Clock Rise and Fall Times
- Capable of Driving Six Low Power TTL Loads, Three Low-Power Schottky Loads, or Six HTL Loads Over the Rated Temperature Range
- Symmetrical Output Characteristics
- 100% Tested for Quiescent Current at 20V
- . 5V, 10V, and 15V Parametric Ratings
- Meets All Requirements of JEDEC Standard No. 13B, "Standard Specifications for Description of 'B' Series CMOS Devices"

Description

CD4541B programmable timer consists of a 16-stage binary counter, an oscillator that is controlled by external R-C components (2 resistors and a capacitor), an automatic power-on reset circuit, and output control logic. The counter increments on positive-edge clock transitions and can also be reset via the MASTER RESET input.

Pinout

CD4541B (CERDIP, PDIP, SOIC, SOP, TSSOP)



The output from this timer is the Q or \overline{Q} output from the 8th, 10th, 13th, or 16th counter stage. The desired stage is chosen using time-select inputs A and B (see Frequency Select Table).

The output is available in either of two modes selectable via the MODE input, pin 10 (see Truth Table). When this MODE input is a logic "1", the output will be a continuous square wave having a frequency equal to the oscillator frequency divided by 2^N . With the MODE input set to logic "0" and after a MASTER RESET is initiated, the output (assuming Q output has been selected) changes from a low to a high state after 2^{N-1} counts and remains in that state until another MASTER RESET pulse is applied or the MODE input is set to a logic "1".

Timing is initialized by setting the AUTO RESET input (pin 5) to logic "0" and turning power on. If pin 5 is set to logic "1", the AUTO RESET circuit is disabled and counting will not start until after a positive MASTER RESET pulse is applied and returns to a low level. The AUTO RESET consumes an appreciable amount of power and should not be used if low-power operation is desired. For reliable automatic power-on reset, $V_{\mbox{\scriptsize DD}}$ should be greater than 5V.

The RC oscillator, shown in Figure 2, oscillates with a frequency determined by the RC network and is calculated using:

$$f = \frac{1}{2.3~R_{TC}C_{TC}} \qquad \begin{array}{ll} \text{Where f is between 1kHz} \\ \text{and 100kHz} \\ \text{and } R_S \geq 10 \text{k}\Omega \text{ and } \approx 2R_{TC} \end{array}$$

Ordering Information

PART NUMBER	TEMP. RANGE (°C)	PACKAGE
CD4541BF3A	-55 to 125	14 Ld CERDIP
CD4541BE	-55 to 125	14 Ld PDIP
CD4541BM	-55 to 125	14 Ld SOIC
CD4541BMT	-55 to 125	14 Ld SOIC
CD4541BM96	-55 to 125	14 Ld SOIC
CD4541BNSR	-55 to 125	14 Ld SOP
CD4541BPW	-55 to 125	14 Ld TSSOP
CD4541BPWR	-55 to 125	14 Ld TSSOP

NOTE: When ordering, use the entire part number. The suffixes 96 and R denote tape and reel. The suffix T denotes a small-quantity reel of 250.

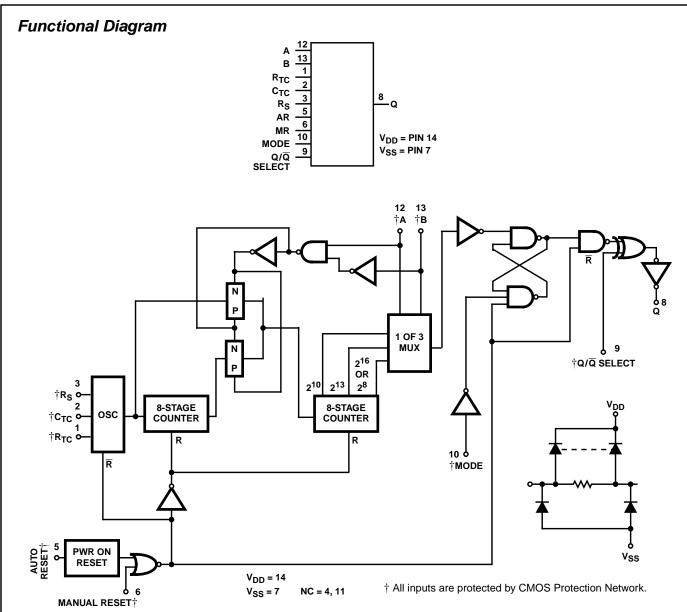


FIGURE 1.

FREQUENCY SELECTION TABLE

Α	В	NO. OF STAGES N	COUNT 2 ^N
0	0	13	8192
0	1	10	1024
1	0	8	256
1	1	16	65536

TRUTH TABLE

	STATE								
PIN	0	1							
5	Auto Reset On	Auto Reset Disable							
6	Master Reset Off	Master Reset On							
9	Output Initially Low After Reset (Q)	Output Initially High After Reset $(\overline{\mathbb{Q}})$							
10	Single Transition Mode	Recycle Mode							

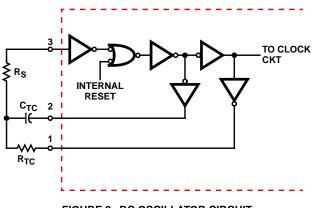


FIGURE 2. RC OSCILLATOR CIRCUIT

CD4541B

Absolute Maximum Ratings

Operating Conditions

For T_A = Full Package Temperature Range 3V (Min), 18V (Typ)

Thermal Information

Package Thermal Impedance, θ_{JA} (see Note 1)
PDIP package
SOIC package
SOP package76°C/W
TSSOP package113°C/W
Maximum Junction Temperature (Plastic Package) 150°C
Maximum Storage Temperature Range (T _{STG})65°C to 150°C
Maximum Lead Temperature (Soldering 10s)
At Distance $1/16$ in $\pm 1/32$ in $(1.59$ mm ± 0.79 mm)
from case for 10s Maximum265°C
(SOIC - Lead Tips Only)

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTE

1. The package thermal impedance is calculated in accordance with JESD 51-7.

Electrical Specifications

	CC	ONDITION	s	LIMITS AT INDICATED TEMPERATURES (°C)							
	,	v	V						25		
PARAMETER	V _O (V)	V _{IN} (V)	V _{DD} (V)	-55	-40	85	125	MIN	TYP	MAX	UNITS
Quiescent Device	-	0, 5	5	5	5	150	150	-	0.04	5	μΑ
Current, (Note 2) I _{DD} (Max)	-	0, 10	10	10	10	300	300	-	0.04	10	μА
	-	0, 15	15	20	20	600	600	-	0.04	20	μΑ
	-	0, 20	20	100	100	3000	3000	-	0.08	100	μА
Output Low (Sink)	0.4	0, 5	5	1.9	1.85	1.26	1.08	1.55	3.1	-	mA
Current I _{OL} (Min)	0.5	0, 10	10	5	4.8	3.3	2.8	4	8	-	mA
	1.5	0, 15	15	12.6	12	8.4	7.2	10	20	-	mA
Output High (Source)	4.6	0, 5	5	-1.9	-1.85	-1.26	-1.08	-1.55	-3.1	-	mA
Current, I _{OH} (Min)	2.5	0, 5	5	-6.2	-6	-4.1	-3	-5	-10	-	mA
	9.5	0, 10	10	-5	-4.8	-3.3	-2.8	-4	-8	-	mA
	13.5	0, 15	15	-12.6	-12	-8.4	-7.2	-10	-20	-	mA
Output Voltage:	-	0, 5	5	-	0.05		-	0	0.05	V	
Low-Level, V _{OL} (Max)	-	0, 10	10	-		0.05		-	0	0.05	V
	-	0, 15	15	-		0.05		-	0	0.05	V
Output Voltage:	-	0, 5	5	-		4.95		4.95	5	-	V
High-Level, V _{OH} (Min)	-	0, 10	10	-		9.95		9.95	10	-	V
	-	0, 15	15	-		14.95		14.95	15	-	V
Input Low Voltage,	0.5, 4.5	-	5	-		1.5		-	-	1.5	V
V _{IL} (Max)	1, 9	-	10	-		3		-	-	3	V
	1.5, 13.5	-	15	-		4		-	-	4	V

CD4541B

Electrical Specifications (Continued)

	CC	ONDITION	s	LIMITS AT INDICATED TEMPERATURES (°C)							
	V-	V	V						25		
PARAMETER	V _O (V)	V _{IN} (V)	V _{DD} (V)	-55	-40	85	125	MIN	TYP	MAX	UNITS
Input High Voltage,	0.5, 4.5	-	5	-		3.5		3.5	-	-	V
V _{IH} (Min)	1, 9	-	10	-		7		7	-	-	V
	1.5, 13.5	-	15	-		11		11	-	-	V
Input Current, I _{IN} (Max)	-	0, 18	18	±0.1	±0.1	±1	±1	-	±10 ⁻⁵	±0.1	μΑ

NOTE:

2. With AUTO RESET enabled, additional current drain at 25°C is:

 $7\mu A$ (Typ), $200\mu A$ (Max) at 5V; $30\mu A$ (Typ), $350\mu A$ (Max) at 10V; $80\mu A$ (Typ), $500\mu A$ (Max) at 15V

Dynamic Electrical Specifications $T_A = 25^{\circ}C$, Input t_r , $t_f = 20$ ns, $C_L = 50$ pF, $R_L = 200$ k Ω

PARAMETER	SYMBOL	V _{DD} (V)	MIN	TYP	MAX	UNITS
Propagation Delay Times	(2 ⁸) t _{PHL} , t _{PLH}	5	-	3.5	10.5	μs
Clock to Q		10	-	1.25	3.8	μs
		15	-	0.9	2.9	μs
	(2 ¹⁶) t _{PHL} , t _{PLH}	5	-	6.0	18	μs
		10	-	3.5	10	μs
		15	-	2.5	7.5	μs
Transition Time	t _{THL}	5	-	100	200	ns
		10	-	50	100	ns
		15	-	40	80	ns
	t _{THL}	5	-	180	360	ns
		10	-	90	180	ns
		15	-	65	130	ns
MASTER RESET, CLOCK		5	900	300	-	ns
Pulse Width		10	300	100	-	ns
		15	225	85	-	ns
Maximum Clock Pulse Input	f _{CL}	5	-	1.5	-	MHz
Frequency		10	-	4	-	MHz
		15	-	6	-	MHz
Maximum Clock Pulse Input Rise or Fall time	t _r , t _f	5, 10, 15		Unlimited		μs

Digital Timer Application

A positive pulse on MASTER RESET resets the counters and latch. The output goes high and remains high until the number of pulses, selected by A and B, are counted. This circuit is retriggerable and is as accurate as the input frequency. If additional accuracy is desired, an external clock can be used on pin 3. A setup time equal to the width of the one-shot output is required immediately following initial power up, during which time the output will be high.

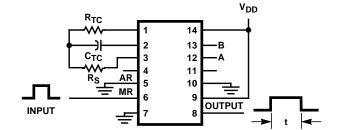


FIGURE 3. DIGITAL TIMER APPLICATION CIRCUIT







PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
CD4541BE	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD4541BEE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD4541BF	ACTIVE	CDIP	J	14	1	TBD	Call TI	N / A for Pkg Type
CD4541BF3A	ACTIVE	CDIP	J	14	1	TBD	Call TI	N / A for Pkg Type
CD4541BM	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR
CD4541BM96	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR
CD4541BM96E4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR
CD4541BME4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR
CD4541BMT	ACTIVE	SOIC	D	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR
CD4541BMTE4	ACTIVE	SOIC	D	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR
CD4541BNSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4541BNSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4541BPW	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4541BPWE4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4541BPWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4541BPWRE4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.



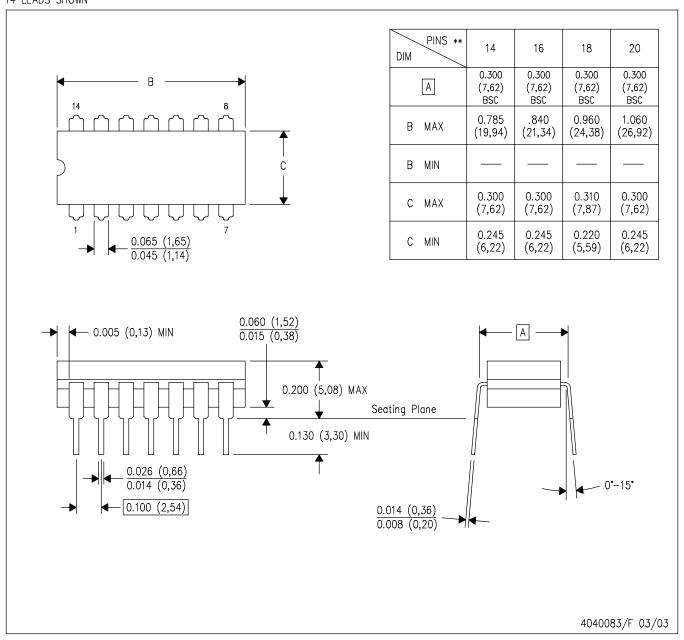
PACKAGE OPTION ADDENDUM

12-Jan-2006

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

14 LEADS SHOWN

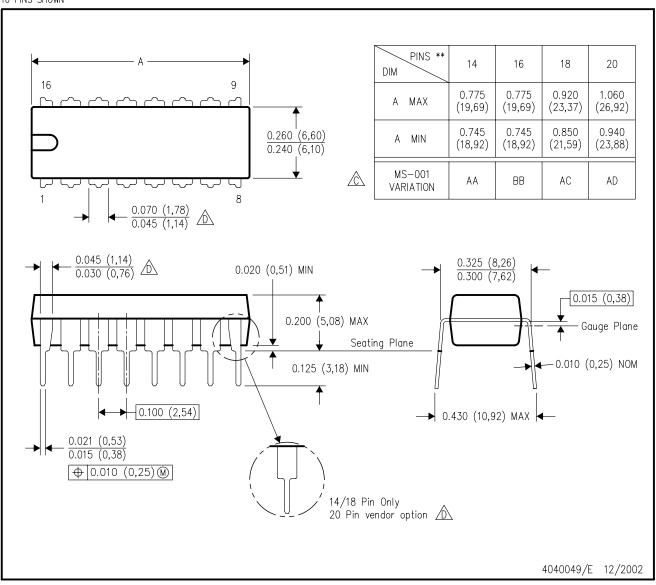


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN

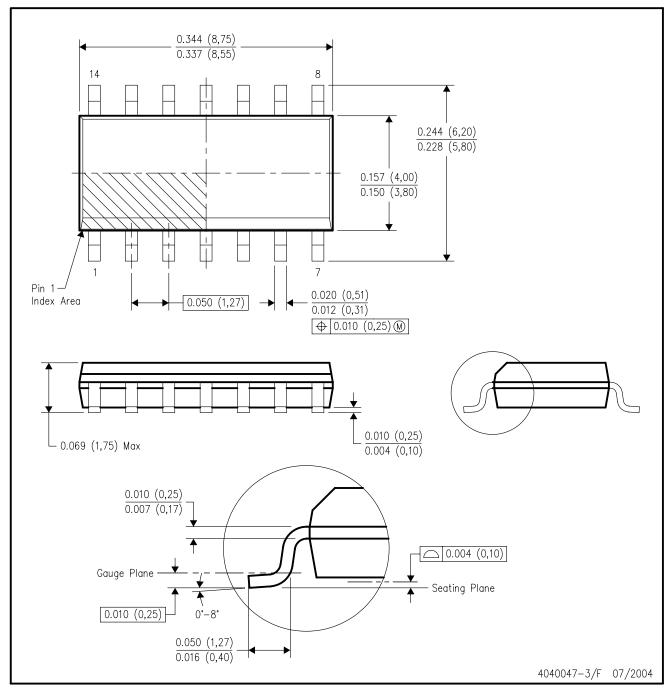


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012 variation AB.

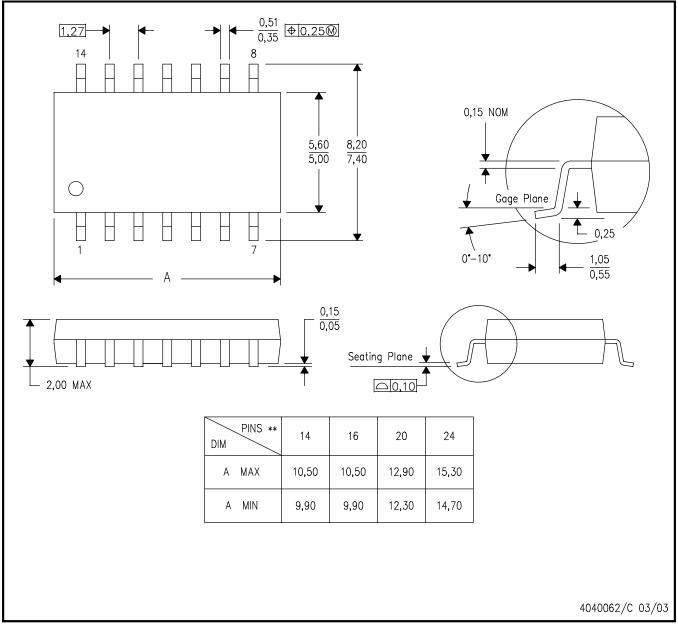


MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



PW (R-PDSO-G**)

14 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products		Applications	
Amplifiers	amplifier.ti.com	Audio	www.ti.com/audio
Data Converters	dataconverter.ti.com	Automotive	www.ti.com/automotive
DSP	dsp.ti.com	Broadband	www.ti.com/broadband
Interface	interface.ti.com	Digital Control	www.ti.com/digitalcontrol
Logic	logic.ti.com	Military	www.ti.com/military
Power Mgmt	power.ti.com	Optical Networking	www.ti.com/opticalnetwork
Microcontrollers	microcontroller.ti.com	Security	www.ti.com/security
		Telephony	www.ti.com/telephony
		Video & Imaging	www.ti.com/video
		Wireless	www.ti.com/wireless

Mailing Address: Texas Instruments

Post Office Box 655303 Dallas, Texas 75265

Copyright © 2006, Texas Instruments Incorporated